



Press Release

KIOXIA at Mobile World Congress 2024

Presenting at two locations: the Hewlett Packard Enterprise booth 3N10 in Hall 3 and the executive meeting rooms in the Hall South Village



Düsseldorf, Germany, 22nd February 2024 – [KIOXIA Europe](#) announced that it is participating at this year's Mobile World Congress in Barcelona from 26th February to 29th February 2024. KIOXIA will join Hewlett Packard Enterprise (HPE) at booth 3N10 in Hall 3 to present their collaboration on the recently launched^[1] HPE Spaceborne Computer-2 to conduct scientific experiments at the International Space Station (ISS).

KIOXIA will be featuring its flash memory-based product lineup of Value SAS and NVMe SSDs (RM, CM and XG), the robust flash storage provided to HPE's Spaceborne Computer-2 comprising Edgeline and ProLiant servers. Flash memory-based SSDs can withstand the harsh

outer space environment as they are less susceptible to electromagnetic waves and have no moving parts, unlike hard disk drive storage. SSDs can deliver faster performance, power efficiency and reliability required.

Overall, KIOXIA provided eight 1,024 gigabytes (GB) NVMe, four 960 GB value SAS SSDs and four enterprise SAS SSDs, each 30.72 terabytes (TB). With more than 130 TB, this is the highest amount of data storage to have ever travelled to the space station on a single mission.

“We are looking forward to joining HPE at their stand 3N10 in Hall 3 at Mobile World Congress,” said Paul Rowan, Chief Marketing Officer & Vice President at KIOXIA Europe GmbH. “Partnering for many years with HPE, our collaboration extends to a broad range of HPE solutions from mobile to cloud and enterprise applications.”

Beyond this collaboration, KIOXIA will also show its Enterprise SDD and Data Center SDD line-up, highlighting Enterprise Data Center Storage Form Factor (EDSFF) E3.S at the executive meeting rooms in Hall South Village. In addition, visitors will be able to learn more about the company’s e-MMC and UFS storage solutions based on BiCS FLASH™ 3D flash memory. While e-MMC is ideal for applications requiring less density such as streaming media devices, printers, wearables, and IoT devices, Universal Flash Storage (UFS) 4.0, a JEDEC-standard, non-volatile managed flash device, is designed for high-performance embedded applications in smartphones, automotive systems, tablets, smart speakers, and AR/VR devices.

Find out more about KIOXIA [Enterprise](#) and [Data Center](#) line-ups.

Or, for further information on UFS and e-MMC flash memory, please go to:

<https://www.kioxia.com/en-jp/business/memory/mlc-nand.html>

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Notes:

[1] The NG-20 mission rocket containing the HPE Spaceborne Computer-2 and KIOXIA SSDs was successfully launched at the end of January 2024: <https://europe.kioxia.com/en-europe/business/news/2024/20240130-2.html>

About KIOXIA Europe GmbH

KIOXIA Europe GmbH (formerly Toshiba Memory Europe GmbH) is the European-based subsidiary of KIOXIA Corporation, a leading worldwide supplier of flash memory and solid-state drives (SSDs). From the invention of NAND flash memory to today's breakthrough BiCS FLASH™ 3D flash memory KIOXIA continues to pioneer innovative memory solutions and services that enrich people's lives and expand society's horizons. The company's innovative BiCS FLASH™ 3D flash memory technology is shaping the future of storage in high-density applications, including advanced smartphones, PCs, SSDs, automotive and data centers.

Visit our [KIOXIA website](#)

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